客户图

NOTES:

1. FINISH:
   - 1.1 HOUSING: LCP BLACK, UL94V-0.
   - 1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AERA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
   - 1.3 GROUND: BRASS,80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
   - 2.1 CURRENT RATING: 0.5A;
   - 2.2 VOLTAGE RATING: 50V.
   - 2.3 CONTACT RESISTANCE: 120mΩ MAX.
   - 2.4 INSULATION RESISTANCE: 500MΩ MIN.
   - 2.5 OPERATION TEMPERATURE: -40℃ TO +125℃.

3.ORDER INFORMATION:

66C8-F XXX XX XXX R 01

Pin数码
010:2x05PIN
......
120:2x60PIN

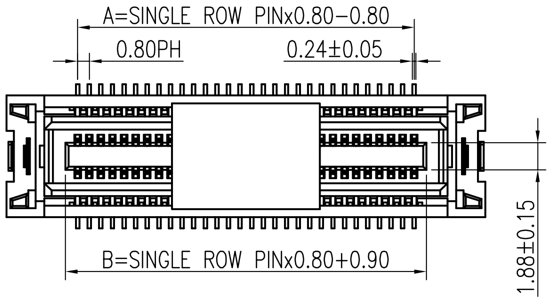
端子电镀：
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G5=15u" Gold
G6=30u" Gold

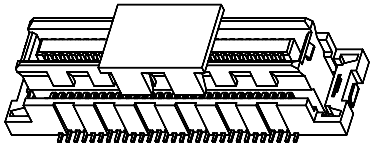
塑胶高度：
049=4.90mm
083=8.30mm

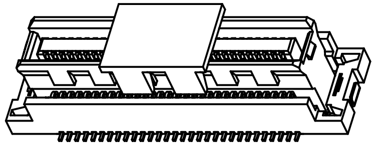
包装方式：
R=TAPE REEL

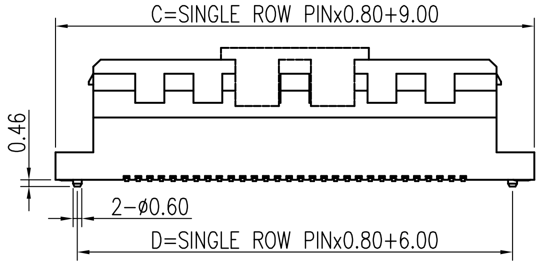
TABLE1:

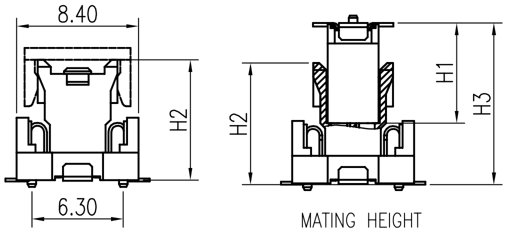
No. OF PIN	A	B	C	D
010=2x05PIN	3.20	4.90	13.00	10.00
020=2x10PIN	7.20	8.90	17.00	14.00
030=2x15PIN	11.20	12.90	21.00	18.00
040=2x20PIN	15.20	16.90	24.00	22.00
050=2x25PIN	19.20	20.90	29.00	26.00
060=2x30PIN	23.20	24.90	33.00	30.00
080=2x40PIN	31.20	32.90	41.00	38.00
100=2x50PIN	39.20	40.90	49.00	46.00
120=2x60PIN	43.20	44.90	53.00	50.00

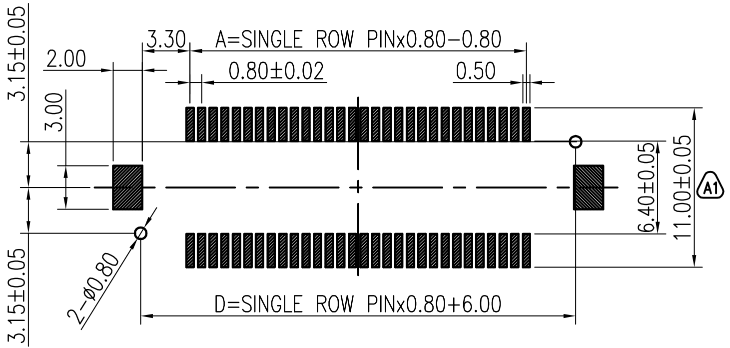



2*40PIN ~ 2*60PIN


2*5PIN ~ 2*30PIN







RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT	H1	H2	H3
6.50mm	4.80	4.90	6.50
8.00mm	6.80		8.00
9.00mm	7.80		9.00
9.75mm	4.80	8.30	9.75
11.75mm	6.80		11.75
12.75mm	7.80		12.75

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A4	2022.08.02	柱子高度由0.60改回0.46	WLY	
A3	2022.06.10	柱子加高到0.6，80PIN以上增加台阶释放应力	WLY	
A2	2022.05.07	更新PCB LAYOUT	WLY	
A0		NEW	——	——

OPERATION				
X.X	±0.40	DESIGN	Jensen	2022.08.02
X.XX	±0.25	CHECK	Jack	2022.08.02
X.XXX	±0.15			
Angle	±3°	APPROVE	Andy	2022.08.02
DIM.	TOL	UNIT	mm	SCALE 1:1

DRAW	WLY	2022.08.02

SOLEPiN **东莞市硕品电子有限公司**
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	66C8-FXXXXXXXXR01
SHEET	1/1	TITLE:	浮动BTB PH0.80mm 母座直立式SMT
PROJ.	⊕◁	DRAW NO.	SP-366

客户图

NOTES:
1. FINISH:
   1.1 HOUSING: LCP BLACK, UL94V-0.
   1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AERA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
   1.3 GROUND: BRASS,80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
   2.1 CURRENT RATING: 0.5A.
   2.2 VOLTAGE RATING: 50V.
   2.3 CONTACT RESISTANCE: 120mΩ MAX.
   2.4 INSULATION RESISTANCE: 500MΩ MIN.
   2.5 OPERATION TEMPERATURE: -40°C TO +125°C.
3. ORDER INFORMATION:

66C8-M XXX XX XXX R 01

Pin数码
010:2x05PIN
......
120:2x60PIN

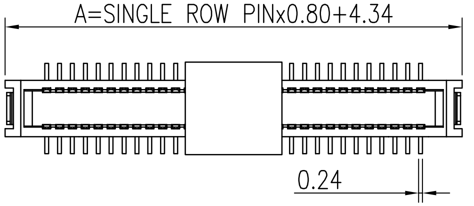
端子电镀:
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G5=15u" Gold
G6=30u" Gold

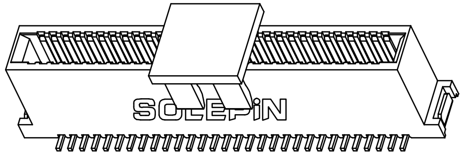
塑胶高度:
048=4.80mm("H1")
068=6.80mm("H1")
078=7.80mm("H1")

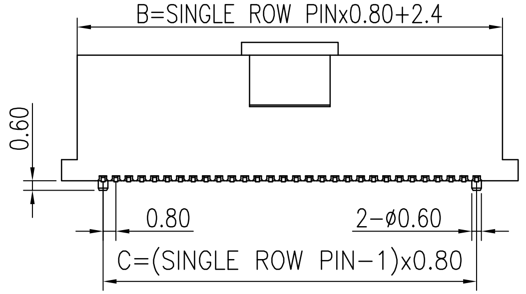
包装方式:
R=TAPE REEL

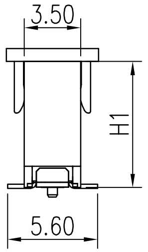
TABLE1:

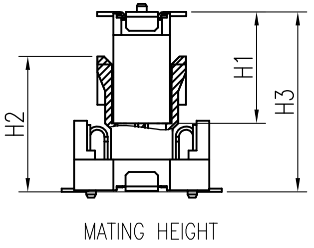
No.OF PIN	Dimensions		
	A	B	C
010=2*05PIN	8.34	6.40	3.20
020=2*10PIN	12.34	10.40	7.20
030=2*15PIN	16.34	14.40	11.20
040=2*20PIN	20.34	18.40	15.20
050=2*25PIN	24.30	22.40	19.20
060=2*30PIN	28.34	26.40	23.20
080=2*40PIN	36.34	34.40	31.20
100=2*50PIN	44.34	42.40	39.20
120=2*60PIN	52.34	50.40	47.20



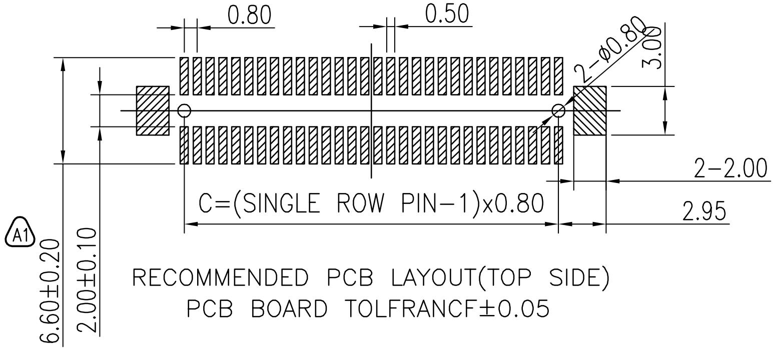








MATING HEIGHT



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT	H1	H2	H3
6.50mm	4.80	4.90	6.50
8.00mm	6.80		8.00
9.00mm	7.80		9.00
9.75mm	4.80	8.30	9.75
11.75mm	6.80		11.75
12.75mm	7.80		12.75

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A2	2022.05.07	更新PCB LAYOUT	WLY	
A1	2021.06.21	PIN针焊盘宽度由5.95修改为6.35	WLY	
A0		NEW	——	——

OPERATION	
X.X	±0.40
X.XX	±0.25
X.XXX	±0.15
Angle	±3°
DIM.	TOL.

DRAW	WLY	2022.05.07
DESIGN	Jensen	2022.05.07
CHECK	Jack	2022.05.07
APPROVE	Andy	2022.05.07
UNIT	mm	SCALE 1:1

SOLEPiN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	66C8-MXXXXXXXXR01
SHEET	1/1	TITLE:	浮动BTB PH0.80mm 公头直立式SMT TYPE
PROJ.	⌖	DRAW NO.	SP-319

客户图

NOTES:

1. FINISH:
   - 1.1 HOUSING: LCP BLACK, UL94V-0.
   - 1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AERA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
   - 1.3 GROUND: BRASS,80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
   - 2.1 CURRENT RATING: 0.5A;
   - 2.2 VOLTAGE RATING: 50V.
   - 2.3 CONTACT RESISTANCE: 120mΩ MAX.
   - 2.4 INSULATION RESISTANCE: 500MΩ MIN.
   - 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3.ORDER INFORMATION:

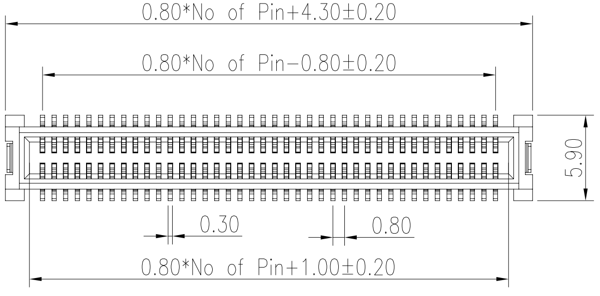
66C8-M XXX XX XXX R 01

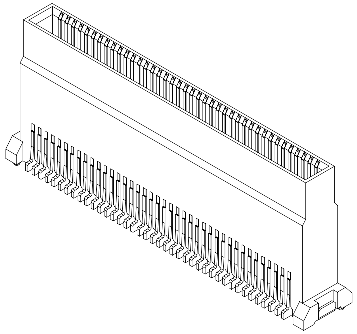
Pin数码
010:2x05PIN
020:2*10PIN
030:2*15PIN
040:2*20PIN
050:2*25PIN
060:2*30PIN
080:2*40PIN

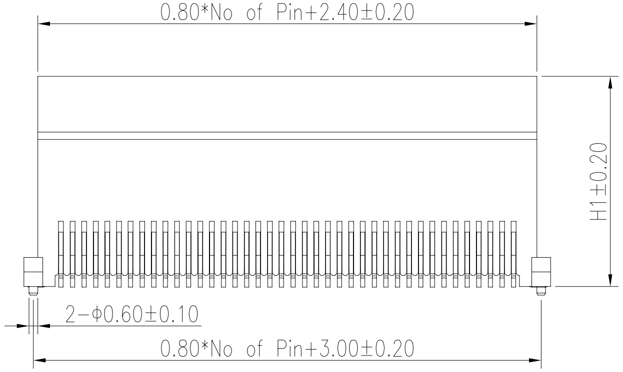
端子电镀：
G0=Gold Flash
G1=1u″ Gold
G2=3u″ Gold
G3=5u″ Gold
G4=10u″ Gold
G5=15u″ Gold
G6=30u″ Gold

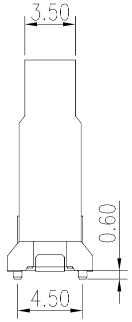
塑胶高度：H1
109=10.95
130=13.05
145=14.55

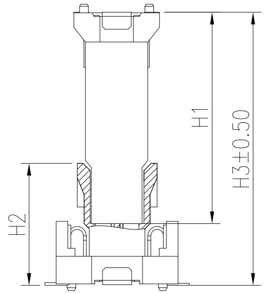
包装方式：
R=TAPE REEL



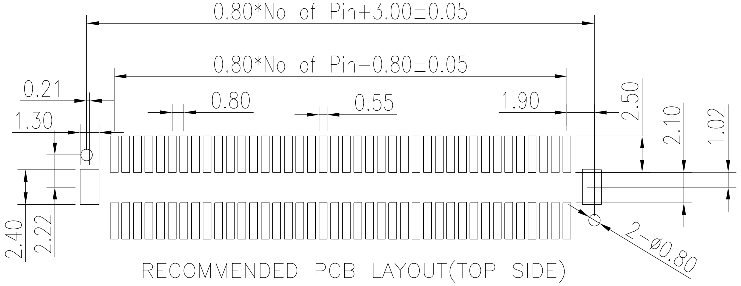








X Y floating ± 0.50 mm



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT

MATING HEIGHT	H1	H2	H3
12.15mm	10.95	4.90	12.15
14.25mm	13.05		14.25
15.75mm	14.55		15.75
15.90mm	10.95	8.30	15.90
18.00mm	13.05		18.00
19.50mm	14.55		19.50

			WLY	
			WLY	
			WLY	
A0		NEW	———	———
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE

OPERATION		DRAW	WLY	2022.08.02
X.X	±0.40	DESIGN	Jensen	2022.08.02
X.XX	±0.25	CHECK	Jack	2022.08.02
X.XXX	±0.15	APPROVE	Andy	2022.08.02
Angle	±3°			
DIM.	TOL	UNIT	mm	SCALE 1:1

SOLEPiN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	66C8-MXXXXXXXXR01
SHEET	1/1	TITLE:	浮动BTB PH0.80mm 公座直立式SMT
PROJ.	⌖	DRAW NO.	SP-1088